

Final Product Change Notification

Issue Date: 20-May-2015 Effective Date: 01-Sep-2015

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201504018F01



Management Summary

Standardization of the backend of EZHV single metal.

Change Category

[X] Wafer Fab process	[] Assembly Process	[] Product Marking	[] Design
[] Wafer Fab materials	[] Assembly Materials	[] Electrical spec./Test coverage	[] Mechanical Specification
[] Wafer Fab location	[] Assembly Location	[] Test Location	[] Packing/Shipping/Labeling

Standardization of the backend of EZHV single metal

Details of this Change

The original EZHV processes have a passivation stack containing a SiN layer at the bottom and a PSG top layer. The altered EZHV passivation comprises a PSG bottom layer and SiN top layer.

This process stack is in use for other wafer processes, such as ABCD3HV.

Why do we Implement this Change

Standardization for backend part of the manufacturing process at the ICN8 waferfab in Nijmegen.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 11-Aug-2015

Impact

no impact to the product's functionality anticipated.

No change in form, fit and function.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 19-Jun-2015.

Remarks

n.a.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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SSL5015TE/1Y	935303721518
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